



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT(s): Kim et al.

SERIAL NO.: 10/678,655

ART UNIT: 2274

FILED: October 2, 2003

EXAMINER: Not yet assigned

ATTORNEY DOCKET NO.: 873.0125.U1(US)

TITLE: Lead-Free Solder Alloys and Methods of Making Same

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

REQUEST FOR CORRECTED FILING RECEIPT

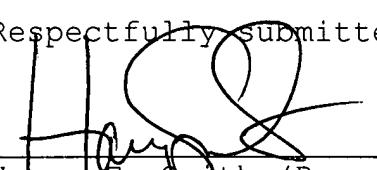
Sir:

Please correct applicant's name for this application as follows:

Viswanadham Puligandla

Attached are copies of the first page of the Application and the first page of the Application Transmittal form which show the correct spelling of applicant's name. Also attached is a copy of the official Filing Receipt for this application.

Respectfully submitted,


Harry F. Smith (Reg. No. 32,493)

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1-19-2004
Date

CERTIFICATION OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service by regular mail service under 37 CFR 1.10 on the date indicated below and addressed to the Commissioner For Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

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APPL NO.	FILING OR 371 (c) DATE	ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLMS	IND CLMS
10/678,655	10/02/2003	1742	2274	873.0125.U1(US)	10	51	14

CONFIRMATION NO. 9762

FILING RECEIPT



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29683

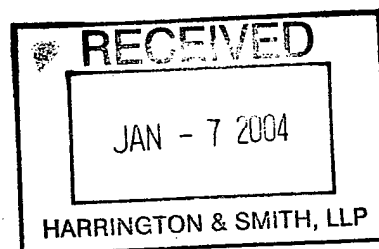
HARRINGTON & SMITH, LLP
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Date Mailed: 01/05/2004

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Applicant(s)

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 Steven Dunford, Lewisville, TX;
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Assignment For Published Patent Application

Nokia Corporation, Espoo, FINLAND;
 Board of Regents, University of Texas System, Austin, TX;

Domestic Priority data as claimed by applicant

This appln claims benefit of 60/479,639 06/19/2003

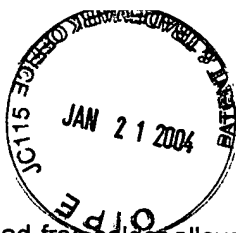
Foreign Applications

If Required, Foreign Filing License Granted: 01/02/2004

Projected Publication Date: 12/23/2004

Non-Publication Request: No

Early Publication Request: No

**Title**

Lead-free solder alloys and methods of making same

Preliminary Class

420

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Title 35, United States Code, Section 184
Title 37, Code of Federal Regulations, 5.11 & 5.15**

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873.0125.U1(US)

NCP34839

Patent Application Papers Of:

Choong-Un Kim

Jae-Yong Park

Rajendra Kabade

Ted Carper

Steven Dunford

Viswanadham Puligandla

**For: LEAD-FREE SOLDER ALLOYS AND
METHODS OF MAKING SAME**



Attorney Docket No.: 873.0125.U1(US)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Mail Stop: NEW PATENT APPLICATION

P.O. Box 1450

Alexandria, VA 22313-1450

NEW APPLICATION TRANSMITTAL FORM

Sir:

Transmitted herewith for filing is the patent application of

Inventor(s): **Choong-Un Kim, Jae-Yong Park, Rajendra R. Kabade,
Ted Carper, Steven Dunford, Viswanadham Puligandla**

For (title): **Lead-Free Solder Alloys And Methods Of Making Same**

Enclosed are the following:

- ☒ Application Cover Page
- ☒ 30 pages of Specification that consists of, 22 pages of Description, 7 pages of Claims and 1 page of Abstract;
- ☒ 10 sheet of drawings;
- ☒ Inventor(s) Declaration;
- ☐ Preliminary Amendment;
- ☒ Priority is hereby claimed from:
 - U.S. Provisional Patent Application Number 60/479,639 filed on June 19, 2003;**
 - Patent Application Number filed on ;
 - Patent Application Number filed on ;
- ☐ Certified Copy of priority document(s);
- ☐ English language translation of priority document;
- ☐ Application Data Sheet;
- ☐ Information Disclosure Statement and/or Form PTO 1449 and cited art;
- ☒ Assignment and Recordation Form Cover Sheet;(2)
- ☒ Return Receipt Postcard;
- ☐ Other: